

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7511350

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KENGO KOBAYASHI	11/23/2020
SHINYA NISHIMURA	11/23/2020
HIROHITO FUJIWARA	11/23/2020
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECH SCIENCE CORPORATION
Street Address:	17-1, TORANOMON 1-CHOME
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-6411
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17130233
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	102877.0050
NAME OF SUBMITTER:	PHILIP W. HARRIS
SIGNATURE:	/Philip W. Harris, Reg. No. 70,011/
DATE SIGNED:	08/30/2022
Total Attachments: 3	
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ASSIGNMENT

WHEREAS, WE,

KOBAYASHI, Kengo,

NISHIMURA, Shinya,

FUJIWARA, Hirohito,

a citizen of Japan, having a mailing address located at c/o HITACHI HIGH-TECH SCIENCE CORPORATION, 17-1, Toranomom 1-chome, Minato-ku Tokyo 105-6411, Japan; and a resident of Tokyo/Japan, have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to THERMAL ANALYZER (collectively the “**INVENTIONS**”) for which I have executed and/or may execute one or more patent applications therefor; and

WHEREAS, Hitachi High-Tech Science Corporation (hereinafter “**ASSIGNEE**”), a corporation, having a place of business at 17-1, Toranomom 1-chome, Minato-ku Tokyo 105-6411, Japan, desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). 17/130,233 filed December 22, 2020 Hitachi High-Tech Science Corporation Reference No. 19P00032-US (and do hereby authorize **ASSIGNEE** and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I further do acknowledge and agree that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said **INVENTIONS**, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in any foreign country, countries, or treaty/union organizations, and all divisional applications,

renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND I DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND I DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I may be entitled, or that I may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I HEREBY covenant and agree that I will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Tokyo, on November 23, 2020 KOBAYASHI KENGO
LOCATION DATE **KOBAYASHI, Kengo**

Done at Tokyo, on November 23, 2020 NISHIMURA Shinya
LOCATION DATE **NISHIMURA, Shinya**

Done at Tokyo, on November 23, 2020 FUJIWARA Hirohito
LOCATION DATE **FUJIWARA, Hirohito**